FINAL PRODUCT/PROCESS CHANGE NOTIFICATION #16627

Generic Copy

Issue Date: 12-Apr-2011

TITLE: Final Notification for Transfer of EMI Filters from ON Semiconductor ZR Fab in Phoenix (USA) to ON Semiconductor ISMF Fab in Seremban (Malaysia).

PROPOSED FIRST SHIP DATE: 12-Jul-2011

AFFECTED CHANGE CATEGORY(S): ON Semiconductor Fab Site

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:
Contact your local ON Semiconductor Sales Office or Yew Hee Soon <y.soon@onsemi.com>

SAMPLES: Contact your local ON Semiconductor Sales Office

ADDITIONAL RELIABILITY DATA: Available
Contact your local ON Semiconductor Sales Office or Laura Rivers <laura.rivers@onsemi.com>

NOTIFICATION TYPE:

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <quality@onsemi.com>.

DESCRIPTION AND PURPOSE:

ON Semiconductor is notifying customers of its plan to transfer EMI Filters products from ON Semiconductor ZR Fab in Phoenix (USA) to ON Semiconductor ISMF Fab in Seremban (Malaysia).

The ISMF facility is an ON Semiconductor owned wafer fab that has been producing products for ON Semiconductor since 1998. Several existing technologies within ON Semiconductor’s product families are currently sourced from ISMF, including Zener Diodes, Small Signal Diodes, Small Signal Bipolar Transistor, and USB array filter products. ON Semiconductor Seremban Wafer FAB is an internal factory that is TS16949, ISO-9001 and ISO-14000 certified.

Qualification tests are designed to show that the reliability of transferred devices will continue to meet or exceed ON Semiconductor standards.

Products listed in this final PCN should be transferred to ON Semiconductor ISMF Fab in Seremban (Malaysia) starting 11 July 2011. After 11 July 2011, customer may receive products from either facility.

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RELIABILITY DATA SUMMARY:

Package: DFN8
Qual Vehicle: NUF2114MNT1G

Test:	Conditions:	Interval:	Results
HTRB	TA=125C,80% Rated Voltage	1008 hrs	0/240
Autoclave+PC	Ta=121C RH=100% ~15 psig	96 hrs	0/240
HAST+PC	Ta=130C RH=85% , ~18.8psig bias=80% rated V or100V Max	96 hrs	0/240
TC+PC	Ta= -65 C to 150 C	1000 cyc	0/240
RSH	Ta=260C, 10 sec dwell		0/30
DPA	post TC		0/6
DPA	post HAST		0/6

Package: Flip Chip
Qual Vehicle: NUF2441FCT1G

TC	Ta= -40 C to 125 C	500 cyc	0/240
DPA	post TC		0/6

CHANGED PART IDENTIFICATION:

Affected products from ON Semiconductor with date code 1128 representing WW28, 2011 and greater may be sourced from either the ISMF Fab in Seremban (Malaysia) or the ZR Fab in Phoenix (USA).

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List of affected General Parts:

NUF2441FCT1G
NUF2114MNT1G
NUF2116MNT1G